

Title (en)  
MODULE CONSTRUCTION AND CONNECTION TECHNOLOGY BY MEANS OF METAL SCRAP WEB OR BENT STAMPING PARTS BENT FROM A PLANE

Title (de)  
AUFBAU- UND VERBINDUNGSTECHNIK VON MODULEN MITTELS AUS EINER EBENE HERAUS GEBOGENEN METALLISCHEN STANZGITTER ODER STANZBIEGETEILEN

Title (fr)  
TECHNIQUE DE CONSTRUCTION ET DE RACCORD DE MODULES AU MOYEN D'UN PATRON DE DECOUPAGE METALLIQUE PLIE HORS D'UN PLAN OU DE PIECES DECOUPEES ET PLIEES HORS D'UN PLAN

Publication  
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Application  
**EP 08786502 A 20080728**

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- DE 102007039916 A 20070823

Abstract (en)  
[origin: WO2009024432A1] The present invention relates to modules (1) having at least one unhoused electronic component (2), particularly an unhoused semiconductor component or unhoused semiconductor power component, each having at least one connecting surface (3) disposed on a top side and/or bottom side for electrically contacting and/or mounting, the at least one component (2) being positioned between respective substrates (5) such that the contact surfaces (3) each electrically contact and/or are attached to opposing electrical conductors (7) and/or mounting surfaces on the substrates (5). The aim of the invention is to provide an inexpensive electrical contact, particularly having a high integration density, low-inductance behavior, high current capacity, good cooling, and high reliability under electrical and thermal cyclic loading. The invention is characterized in that at least one metal scrap web or bent stamping part (9) is bent out of a plane of the substrates (5) and can be combined with metal scrap webs or bent stamping parts (11) extending in a plane. The module (1) is particularly suitable for high-voltage applications greater than 1000 V, and corresponding electronic components (2).

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Citation (search report)  
See references of WO 2009024432A1

Citation (examination)  

- US 2005224945 A1 20051013 - SAITO WATARU [JP], et al
- WO 2004053988 A1 20040624 - BOSCH GMBH ROBERT [DE], et al

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